



1732 #4
12-17-02

PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF : KOICHI UCHIYAMA
FOR : STENCIL SHEET, PROCESS FOR
PRODUCING THE SAME, AND PROCESS
FOR PRODUCING STENCIL PLATE
SERIAL NO. : 10/051,786
FILED : January 17, 2002
EXAMINER : Unknown
ART UNIT : 1732
CONFIRMATION NO. : 1542
ATTORNEY DOCKET NO. : KAW 2 0102

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INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner of Patents
Washington, D.C. 20231

Dear Sir:

In accordance with 37 C.F.R. §§ 1.56, 1.97, 1.98 and MPEP § 609, applicant submits the following Disclosure Statement concerning art of which the applicant is aware. A copy of PTO-1449 is enclosed herewith.

This Information Disclosure Statement is not intended to constitute an admission that any patent, publication or other information referred to herein or submitted herewith is "prior art" for this invention unless specifically designated as such.

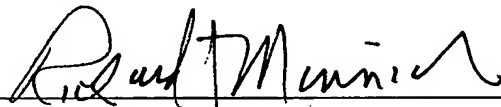
In accordance with 37 C.F.R. §1.97(g) and (h), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made or that no other material information as defined in 37 C.F.R. §1.56(b) exists.

Under § 1.98(a)(3), no concise explanation of relevance is required for information that is in the English language. Accordingly, the enclosed requires no further explanation (or no translation is available).

Under § 1.97(b)(3), this Information Disclosure Statement is being filed before the mailing date of a first Office Action on the merits. Although it is believed no fee is necessary, any deficiency in fees should be charged to Deposit Account No. 06-0308.

It is respectfully requested that the attached documents be considered and officially cited in examination of this application.

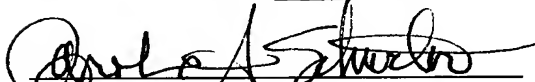
Respectfully submitted,
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CERTIFICATE OF MAILING

I hereby certify that this **Information Disclosure Statement** is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner of Patents, Washington, D.C. 20231, on December 5, 2002.


Caroline A. Schveter